molex

Part Number : 2044731212
Product Description : DDR5 RDIMM Socket, Vertical Surface Mount, 0.76µm Gold Plating, 288 Circuits, PCB Thickness 1.57mm to 3.18mm, Black Housing, Off-White Latch
Series Number : 204473
Status : Active
Product Category : Memory Module Connectors

Documents & Resources

Drawings

2044731212_sd.pdf
2044730003-000.pdf

3D Models and Design Files

2044730000-000.pdf
2044730000-000.zip

Specifications

2044730000-AS-000.pdf
2044730002-000.pdf
2044730001-PS-000.pdf

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	e
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2024)6225-DC (07 Nov 2024)
EU RoHS	Compliant per EU 2015/863

Multiple Part Product Compliance Statements

- Eu RoHS
- REACH SVHC
- Low-Halogen

Multiple Part Industry Compliance Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

EU RoHS Certificate of Compliance

Part Details

General

Status	Active
Category	Memory Module Connectors
Series	204473
Description	DDR5 RDIMM Socket, Vertical Surface Mount, 0.76µm Gold Plating, 288 Circuits, PCB Thickness 1.57mm to 3.18mm, Black Housing, Off-White Latch
Component Type	Socket
JEDEC Outline	MO-329
Product Name	DDR5 DIMM
UPC	191128914444

Agency

CSA	1409726
UL	E29179

Electrical

Current - Maximum per Contact	1.0A
Voltage - Maximum	29V AC (RMS)/DC

Physical

Circuits (Loaded)	288
Circuits (maximum)	288
Durability (mating cycles max)	25
Entry Angle	Vertical (Top Entry)
Flammability	94V-0

Housing Color	Black
Keying to Mating Part	Yes
Latch Color	Natural (Off-White)
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Polyamide
Net Weight	6.289/g
Packaging Type	Tray
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness - Recommended	1.57mm, 3.18mm
Pitch - Mating Interface	0.85mm
Pitch - Termination Interface	0.85mm
Plating min - Mating	0.762µm
Plating min - Termination	2.540µm
Temperature Range - Operating	-55° to +85°C
Termination Interface Style	Surface Mount

Solder Process Data

Max-Duration	10
Lead-Free Process Capability	REFLOW
Max-Cycle	3
Max-Temp	260

Mates With / Use With

Mates with Part(s)

Description	Part Number
Mates With	Memory Module Cards of 1.27mm Thickness